## CLAIMS

[Claim 1]

A layered sheet comprising:

a substrate layer; and

a surface layer configured to be layered on at least one surface of the substrate layer,

wherein the substrate layer contains a first thermoplastic resin and inorganic fillers,

wherein the surface layer contains a second thermoplastic resin and a conductive material,

wherein a content of the inorganic fillers in the substrate layer is 0.3 to 28 mass% based on a total amount of the substrate layer.

wherein the first thermoplastic resin includes a styrene-based resin, and

wherein the second thermoplastic resin includes a polycarbonate resin and polyester resin.

[Claim 2]

A layered sheet comprising:

a substrate layer; and

a surface layer configured to be layered on at least one surface of the substrate layer,

wherein the substrate layer contains a first thermoplastic resin and inorganic fillers,

wherein the surface layer contains a second thermoplastic resin and a conductive material,

wherein an average primary particle size of the inorganic fillers is 25 nm to 5.0 μm,

wherein a content of the inorganic fillers in the substrate layer is 6 to 28 mass% based on a total amount of the substrate layer,

wherein the first thermoplastic resin includes a high-impact polystyrene resin, and

wherein the second thermoplastic resin includes a high-impact polystyrene resin.

[Claim 3]

The layered sheet according to claim 1,

wherein an average primary particle size of the inorganic fillers is 25 nm to 5.0 μm.

[Claim 4]

The layered sheet according to any one of claims 1 to 3,

wherein the substrate layer contains carbon black as the inorganic fillers.

[Claim 5]

The layered sheet according to any one of claims 1 to 4,

wherein the substrate layer contains, as the first thermoplastic resin, a thermoplastic resin of the same kind as the second thermoplastic resin contained in the surface layer and contains, as the inorganic fillers, inorganic fillers formed of the same material as the conductive material contained in the surface layer.

[Claim 6]

The layered sheet according to any one of claims 1 to 5,

wherein a content of the conductive material in the surface layer is 10 to 30 mass% based on a total amount of the surface layer.

[Claim 7]

The layered sheet according to any one of claims 1 to 6,

wherein a thickness of the substrate layer is 70% to 97% of a thickness of the entire layered sheet.

[Claim 8]

A container configured to be a molded body of the layered sheet according to any one of claims 1 to 7.

[Claim 9]

A carrier tape configured to be a molded body of the layered sheet according to any one of claims 1 to 7 and be provided with an accommodation portion capable of accommodating an article.

[Claim 10]

An electronic component packaging body comprising:

the carrier tape according to claim 9;

an electronic component configured to be accommodated in the accommodation portion of the carrier tape; and

a cover film configured to be adhered to the carrier tape as a lid material.